

1A, 50 - 1000V Surface Mount Rectifier

FEATURES

- Plastic package has carries underwriters
- Ideal for automated placement
- Surge overload rating to 30A peak
- · Reliable low cost construction utilizing molded
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Inverters and Converters
- Free Wheeling diodes

MECHANICAL DATA

- · Case: MELF
- Molding compound meets UL 94V-0 flammability rating
- Meet JESD 201 class 1A whisker test
 Polarity: Indicated by cathode band
 Weight: 120.00mg (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	1	Α		
V_{RRM}	50 - 1000	V		
I _{FSM}	30	Α		
T _{J MAX}	150	°C		
Package	MELF			









MELF

DADAMETED	SYMBOL	LL4001	LL4002	LL4003	LL4004	LL4005	LL4006	LL4007	
PARAMETER	STMBOL	G	G	G	G	G	G	G	UNIT
Repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	35	70	140	280	420	560	700	V
DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Forward current	I _F				1				Α
Surge peak forward current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30			А				
Junction temperature	TJ	-65 to +150			°C				
Storage temperature	T _{STG}	-65 to +150				°C			





THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-case thermal resistance	R _{eJC}	50	°C/W	

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage (1)	I _F = 1.0A	V _F	-	1.1	V
Reverse current @ rated V _R (2)	T _J = 25°C		-	5	μA
Reverse current @ fated v _R	T _J = 125°C	- I _R	-	100	μA
Junction capacitance	1 MHz, V _R =4.0V	CJ	15	-	pF

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
LL400xG L0G	MELF	5,000/13" reel		

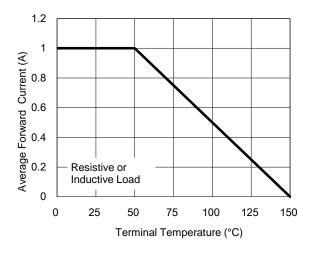
Notes:

(1) "x" defines voltage from 50V(LL4001G) – 1000V(LL4007G)



CHARACTERISTICS CURVES (T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve



Forward Surge Current

Fig.2 Maximum Non-Repetitive Peak

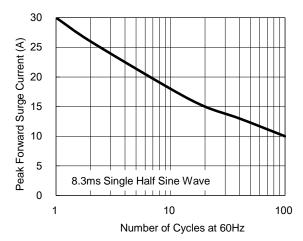


Fig.3 Typical Forward Characteristics

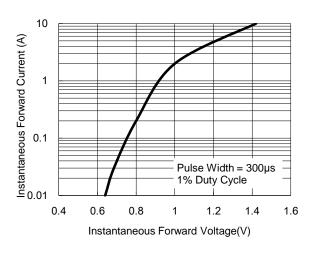


Fig.4 Typical Reverse Characteristics

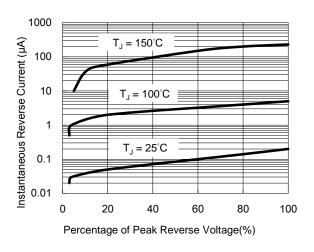


Fig.5 Typical Junction Capacitance

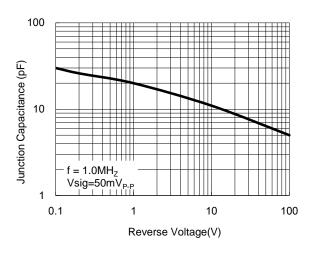
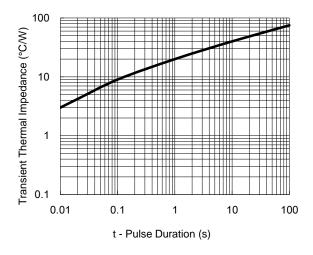


Fig.6 Typical Transient Thermal Impedance

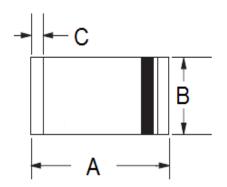






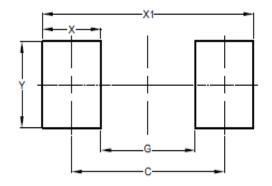
PACKAGE OUTLINE DIMENSIONS

MELF



Unit (mm		(mm)	Unit (inch)		
DIM	Min	Max	Min	Max	
Α	4.80	5.50	0.189	0.217	
В	2.25	2.67	0.089	0.105	
С	0.30	0.60	0.012	0.024	

SUGGESTED PAD LAYOUT



DIM	Unit (mm)	Unit (inch)
DIN	TYP	TYP
С	4.80	0.189
G	3.30	0.130
Х	1.50	0.059
X1	6.30	0.248
Υ	2.70	0.106



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